

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of

Tsai et al

Serial No.: 09/586, 525

Filed: June 2, 2000

For: SUBSTRATE STRUCTURE  
OF FLIP CHIP PACKAGE

Examiner: Ori Nadav

Art Unit: 2811

Docket No.: JCLA5827

4/a  
FJONES  
4-29-02

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on APR 10, 2001

No fee is believed to be due in connection with this amendment and response to Office Action. If, however, any fee is believed to be due, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-0710 (order No. JCLA5827).

Signature

AMENDMENT AND RESPONSE TO FIRST OFFICE ACTION

Assistant Commissioner of Patents and Trademarks  
Washington, DC 20231

Sir:

The Office Action mailed in September 20, 2001 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

In the claims

Sub B<sup>1</sup> Please amend the claims 1, 7 and 12 as follows and please delete claim 6:

1. (Once Amended) A substrate structure of Flip Chip package comprising: